

Abstract

A method for mounting through an anisotropic conductive film defined as an adhesive sheet an electronic component on a printed circuit board (flexible board) provided with a wiring pattern. The anisotropic conductive film is bonded to an area of the flexible board to be mounted with the electronic component in a state where air intervening between the anisotropic conductive film and the flexible board is heated. Since the air confined between the anisotropic conductive film and the flexible board reduces in volume upon cooled down, occurrence of voids, exposure of the wiring pattern, or the like is avoided. Consequently, reliability can be enhanced without complicating the mounting.